## **Supplementary Information**



"Sub-10 nm scalable hybrid dielectric engineering on MoS2 for 2D materials based devices"

Figure S1: MALD hybrid OTS-Al<sub>2</sub>O<sub>3</sub> and OTS-TiO<sub>2</sub> films show constant growth rate of ~0.5 nm/cycle with excellent film uniformity (Top) and thickness scalability down to 2.5 nm on  $MoS_2$  as verified by HR-TEM cross-section images.



Figure S2: Proposed band alignments of OTS/TMA and OTS/TiCl<sub>4</sub> hybrid dielectrics in reference to  $MoS_2$  extracted based on their XPS valence band and O 1s loss features (left). Tunable dielectric constant from 4.5 to 7.8 by changing the inorganic component from Al-O to Ti-O (middle). Top gate modulation of  $MoS_2$  devices with 7.0 nm of OTS/TMA as dielectric (right).